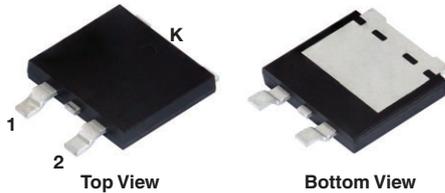


# Dual TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

 Ultra Low  $V_F = 0.29\text{ V}$  at  $I_F = 5\text{ A}$ 

## eSMP<sup>®</sup> Series SMPD (TO-263AC)



### FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code; base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### ADDITIONAL RESOURCES


[3D Models](#)

### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection.

### MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3\_X - halogen-free, RoHS-compliant, and AEC-Q101 qualified

("\_X" denotes revision code e.g. A, B,.....)

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test, HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** as marked

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 15 A
$V_{RRM}$	50 V
$I_{FSM}$	300 A
$V_F$ at $I_F = 15\text{ A}$	0.42 V
$T_J$ max.	150 °C
Package	SMPD (TO-263AC)
Circuit configuration	Common cathode

MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V30DL50C	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$	per device	30
		per diode	15
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	300	A
Operating junction and storage temperature range	$T_J, T_{STG}$	-40 to +150	°C

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
Instantaneous forward voltage per diode	$I_F = 5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.39	-	V
	$I_F = 7.5\text{ A}$			0.42	-	
	$I_F = 15\text{ A}$			0.49	0.57	
	$I_F = 5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.29	-	
	$I_F = 7.5\text{ A}$			0.33	-	
	$I_F = 15\text{ A}$			0.42	0.50	
Reverse current per diode	$V_R = 50\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	-	1800	$\mu\text{A}$
		$T_A = 125\text{ }^\circ\text{C}$		25	60	$\text{mA}$
Typical junction capacitance	4.0 V, 1 MHz	$T_A = 25\text{ }^\circ\text{C}$	$C_J$	2800	-	$\text{pF}$

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: pulse width  $\leq 40\text{ ms}$

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	V30DL50C	UNIT	
Typical thermal resistance	per diode	$R_{\theta JC}$	1.7	$^\circ\text{C/W}$
	per device		0.9	
	per device	$R_{\theta JA}^{(1)(2)}$	45	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
 (2) Free air, without heatsink

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V30DL50C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel
V30DL50CHM3_A/I <sup>(1)</sup>	0.55	I	2000/reel	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

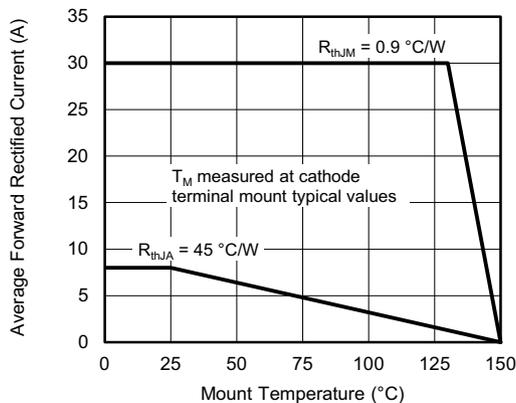
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)


Fig. 1 - Forward Current Derating Curve

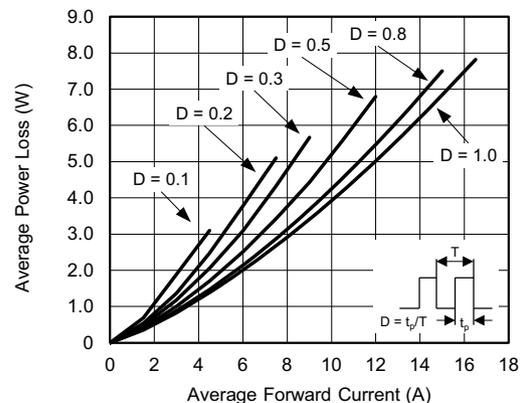


Fig. 2 - Forward Power Loss Characteristics Per Diode

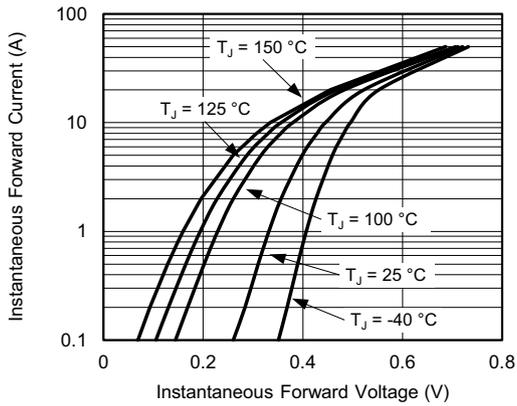


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

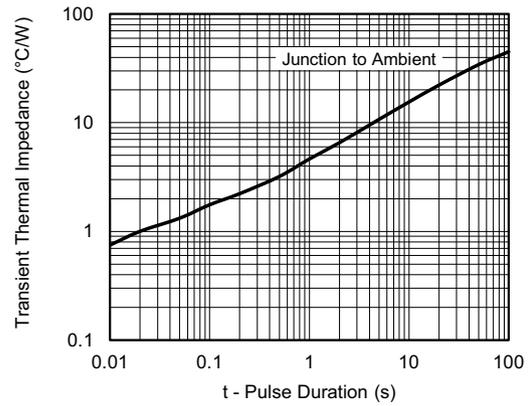


Fig. 6 - Typical Transient Thermal Impedance Per Device

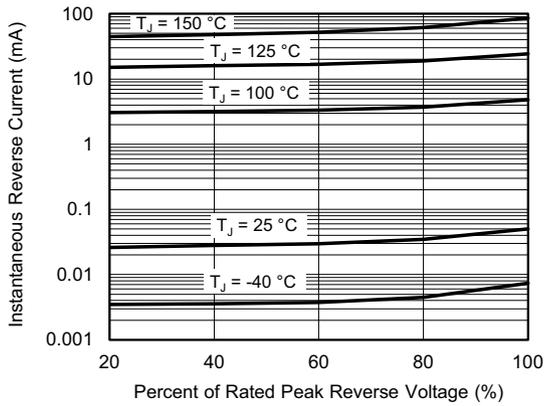


Fig. 4 - Typical Reverse Characteristics Per Diode

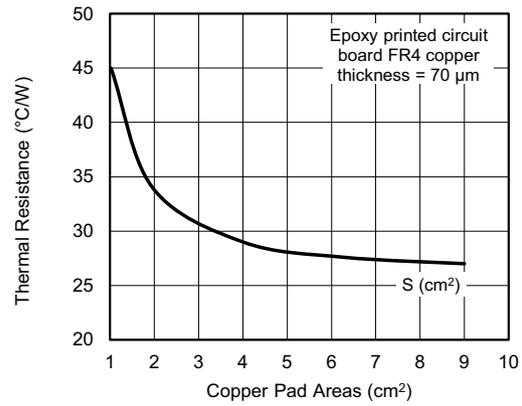


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

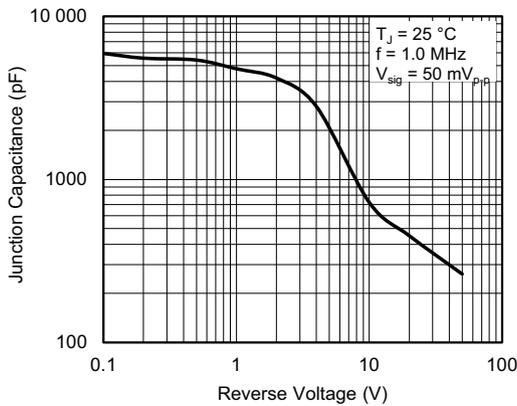
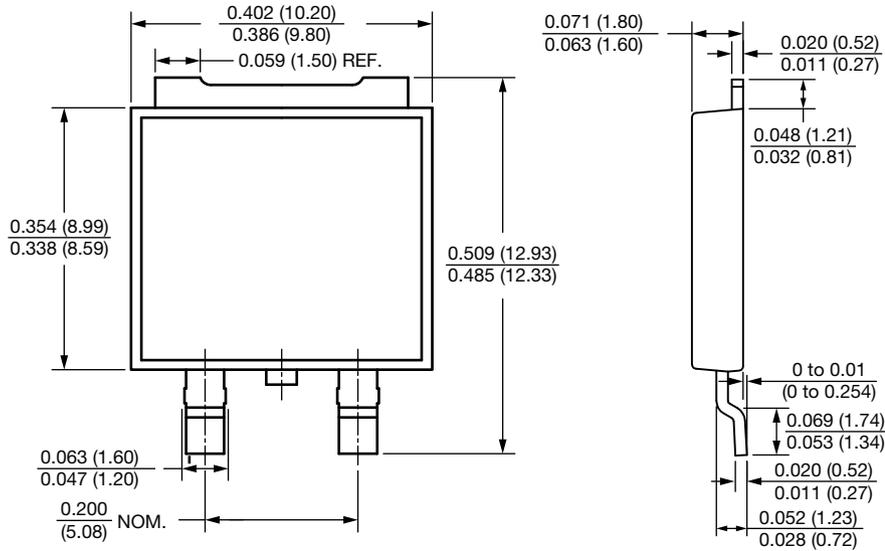


Fig. 5 - Typical Junction Capacitance Per Diode

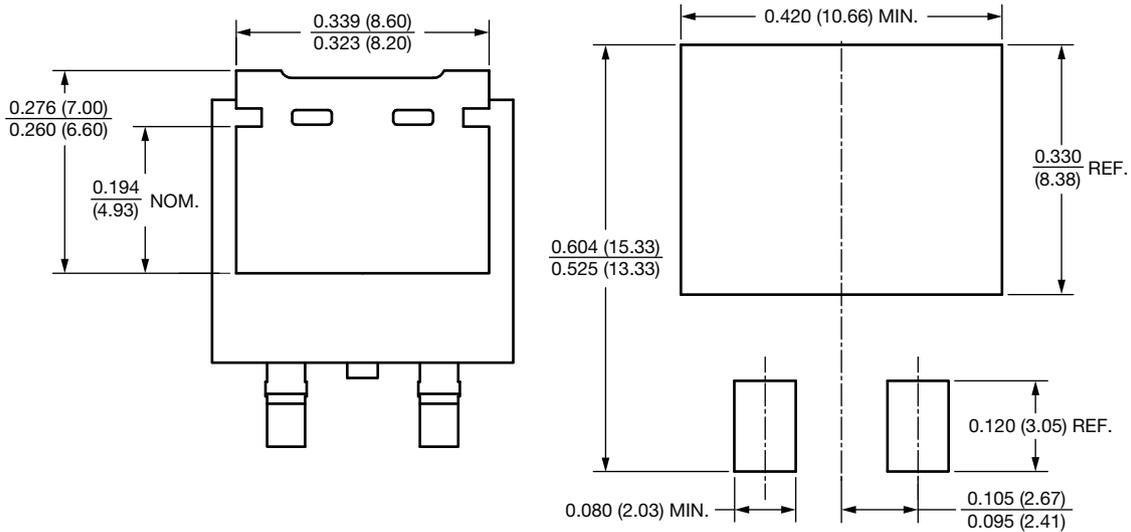


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD (TO-263AC)



Mounting Pad Layout





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